


## Table of Content PCIM Europe 2022

### Keynote

- K01**                    **»Hydrogen – Key Element to Achieve Net Zero CO<sup>2</sup>«**  
Jürgen Rechberger, Vice President Hydrogen & Fuel Cell, AVL List, A
- K02**                    **»Power Electronics for a Future Sustainable Society«**  
Ichiro Omura, Professor, Kyushu Institute of Technology, J
- K03**                    **»From State of the Art to Future Development Trends of Power Supply«**  
Peter Wallmeier, Senior Director, Delta Energy Systems, D

### Special Session: Advanced GaN Power Electronics

- 001**                    **New Technologies for Efficient and Integrated GaN Power Devices**  
Luca Nela, Nirmana Perera, Remco van Erp, Taifang Wang, Elison Matioli, EPFL, CH
- 002**                    **GaN Power Electronics: From Device to System**  
Alex Huang, University of Texas at Austin, USA
- 003**                    **Practical Challenges in the Design of High Density GaN-Based Power Converters**  
Robert Pilawa-Podgurski, University of California, Berkeley, USA
-  **004**                    **Next Generation GaN-Based Architectures: From 240W USB-C Adapters to 11kW EV On-Board Chargers with Ultra-High Power Density and Wide Output Voltage Range**  
Matthias Kasper, Jon Azurza Anderson, Gerald Deboy, Infineon Technologies, A;  
Michael Haider, Power Electronic Systems Laboratory, CH

### Special Session: Cognitive Power Electronics

- 005**                    **The Interplay between Silicon Capability and System Architecture for Cognitive Power Systems**  
Nicolas Lehment, Florian Kälber, Frieder Jaspers, NXP Semiconductors, D
- 006**                    **Cognitive Power Electronics 4.0 – An Enabler for Smart Systems**  
Martin Schellenberger, Bernd Eckardt, Vincent Lorentz, Fraunhofer Institute IISB, D
- 007**                    **Cognitive Power Electronics for Smart Drives in Unmanned Aerial Vehicles**  
Tobias Huf, Georg Roeder, Martin Schellenberger, Fraunhofer Institute IISB, D;  
Harm-Friedrich Steinmetz, mdGroup, D

- 008**                    **Modular Ultra-Low-Power IoT-Core - Bridging the Gap Between Power Electronics and Distributed Sensor Networks**  
Carsten Brockmann, Alireza Rezaei, Jan Hefer, Applikationszentrum am Fraunhofer IZM, D; Frank Oehler, Markus Eppel, Heinrich Milosiu, Fraunhofer Allianz Vision, D; Jan Hager, Holger Gerstner, Bernd Eckardt, Stefan Matlok, Fraunhofer IISB, D; Samer Al-Magazachi, Technical University of Berlin, D

### Special Session: Advanced Measurement Technology in Power Electronics

- 009**                    **Common-Mode / Differential-Mode Noise Separation Using Oscilloscopes for More Efficient EMC Filter Design**  
Marcus Sonst, Markus Herdin, Rohde & Schwarz International, D
- 010**                    **Probing Techniques for GaN Power Electronics: How to Obtain 400+ MHz Voltage and Current Measurement Bandwidths without Compromising PCB Layout**  
Harry Dymond, Bernard Stark, Saeed Jahdi, Yushi Wang, University of Bristol, GB
- 011**                    **Using Near Field Probes in Electronic Circuits**  
Arturo Mediano, University of Zaragoza, E
- 012**                    **How IsoVu Probe Breaks the Barrier of Wide Bandgap Dynamic Testing**  
Pierre Dupont, Tektronix, F

### DC-DC Converters

- 013**                    **Beyond 4 kW/in<sup>3</sup> Power-Density for 48 V to 12 V Conversion using eGaN FETs in an LLC DC-DC Bus Converter**  
Michael de Rooij, Amir Negahdari, Efficient Power Conversion (EPC), USA
- 014**                    **500 kHz SiC- and GaN-Based Dual Active Bridge with Voltage Conversion Between 48 V and 650 V**  
Patrick Lenzen, Martin Pfof, TU Dortmund University, D
- 015**                    **Clamped Topology Morphing of the Isolated Full-Bridge Converter for Reduced Rectifier Semiconductor Blocking Voltages and Transformer Volume**  
Philipp Rehlaender, Joachim Böcker, Frank Schafmeister, Paderborn University, D
- 016**                    **Three-Level Switched Capacitor Resonant Converter-Based DCX**  
Marcelo Lobo Heldwein, Technical University, of Munich, D; Francisco Jose Viglus, Federal University of Santa Catarina, BR

### Battery Chargers

- 017**                    **Tiny Power Box - Exploiting Multiport Series Resonant Topologies for High Power Density Onboard Chargers**  
Franz Vollmaier, Ismail Recepti, Thomas Langbauer, Milan Pajnic, Werner Konrad, Christian Mentin, Silicon Austria Labs, A; Alexander Connaughton, Graz University of Technology, A

- 018**                    **50 kW Modular V2G SiC Charger Station in Energy Island Microgrids: a Real Use-Case in Madeira Island**  
Jesús Muñoz-Cruzado, Erika Laporta Puyal, Antonio Miguel Muñoz Gómez, Javier Ballestín Fuertes, Fundación Circe, E; José Francisco Sanz Osorio, University of Zaragoza, E
- 019**                    **Ultra-Compact Single-Stage Bidirectional Wireless Battery Charger for Electric Vehicles**  
Asier Garcia-Bediaga, Ander Avila, Iñigo Zubitur, Alex Sanchez, Alejandro Rujas, Ikerlan Technology Research Centre, E
- 020**                    **Single-Phase Bidirectional ZVZCS AC-DC Converter for MV-Connected Ultra-Fast Chargers**  
Kaveh Pouresmaeil, Jorge Duarte, Korneel Wijnands, Maurice Roes, Nico Baars, Eindhoven University of Technology, NL

### Packaging Technologies

- 021**                    **A New High Power Density 6-in-1 IGBT Module Enabling Acceleration of Vehicle Electrification**  
Yujiro Takeuchi, Takayuki Kushima, Seiichi Hayakawa, Tetsuo Oda, Masaki Shiraishi, Takayuki Ouchi, Takashi Wada, Hisayuki Tsuruoka, Hisada Kenichi, Masayuki Kamikawa, Toshiki Tanimura, Yukihiro Kumagai, Yutaka Kato, Hitachi Power Semiconductor Device; J
- 022**                    **Design of Wire Bondless Double-Sided Cooled Power Module Using Ceramic Heat Sink and Multilayer Silver Sintering**  
Rabih Khazaka, Safran, F; Didier Bouvard, Jean Michel Missiaen, SIMAP Laboratory, F; Yvan Avenas, Nicolas Botter, G2Elab, F
- 023**                    **Maskless Electroplating Patterning Process using Selective Electrochemical Additive Manufacturing Method for Forming of Cu Pillar Bump, Spacer and Ag Plating on Ceramic Substrate**  
Sung-Bin Kim, Andrea Kim, Kun-Woong Ko, AnyCasting, ROK; Bongyoung Yoo, Hanyang University, ROK

### High Voltage Si Devices

- 024**                    **A 4.5kV RC-IGCT with Diode Segmentation for MMC Inverters**  
Tobias Wikström, Umamaheswara Reddy Vemulapati, Bjoern Oedegard, Hitachi Energy, CH
- 025**                    **Effects of On-State Snap-Back Characteristics on the Current Sharing of Parallel RC-IGBTs**  
Munaf T. Rahimo, MTAL, CH; Paula Diaz Reigosa, ABB, CH; Francesco Iannuzzo, Aalborg University, DK

- 026**                    **2000 V Class LV100 IGBT Module Enabling Higher Power Density and Design Simplification in Renewable 1500 V Inverter Systems**  
Thomas Radke, Eugen Wiesner, Mitsubishi Electric Europe, D; Masaomi Miyazawa, Satoshi Miyahara, Koichi Masuda, Mitsubishi Electric, J

### SiC Devices in Transportation

- 027**                    **SiC-MOSFET Inverter in High-Performance PHEV Applications**  
Maximilian Hofmann, Christian Sülthrop, Fraunhofer Institute IISB, D; Maximilian Barkow, Thomas Hubert, Michael Reinlein, Porsche, D
- 028**                    **Benefits of SiC in On-Board Charger Applications**  
Lisa Holzmann, Ben Rosam, Marco Schmidt, Mark Münzer, Andreas Hürner, Infineon Technologies, D
- 029**                    **A SiC Based 30kW Three Phases Interleaved LLC Converter for EV Fast Charger**  
Chen Wei, Zongzeng Hu, Fulin Zhang, Wolfspeed, CHN; Jianwen Shao, Anui Narain, Wolfspeed, USA

### Advanced IGBTs

- 030**                    **A New Level of Performance: Best-in-Class 900 A and 750 A 1700 V EconoDUAL 3 Modules with TRENCHSTOP IGBT7**  
Aleksei Gurvich, Klaus Vogel, Andreas Schmal, Philipp Ross, Jan Baurichter, Infineon Technologies, D
- 031**                    **Next Generation LV Trench IGBT Design Featuring Plasma-Flow Control for Improved Switching Losses and Turn-on dV/dt Controllability**  
Gaurav Gupta, Elizabeth Buitrago, Nick Schneider, Wolfgang Vitale, Luca De Michielis, Hitachi Energy, CH
- 032**                    **Next Generation 1.7 kV Chipset: Fine-Pattern Trench IGBT and Ultra-Thin FSA Diode for Traction Applications**  
Wolfgang Amadeus Vitale, Gontran Pâques, Boni Boksteen, Gaurav Gupta, Antoni Ruiz, Nicolò Oliva, Luca De Michielis, Elizabeth Buitrago, Nick Schneider, Hitachi Energy, CH
- 033**                    **New SIPOX-JTE (SIPOS/Oxide) Edge Termination Shows Excellent Robustness and 50% Lower Leakage at  $T_j=150\text{ }^\circ\text{C}$  for 6.5kV IGBTs**  
Luther-King Ngwendson, Arthur Su, Yangang Wang, Lee Coulbeck, Dynex Semiconductor, GB

## Converter Control

**034**                    **Flexible Operation of Variable Speed Direct-MMC in Hydropower Applications**  
Philippe Bontemps, EPFL, CH; Drazen Dujic, Power Electronics Laboratory, EPFL, CH



**035**                    **Frequency Control and Inertia Provision with UPS**  
Mario Schweizer, Nicola Notari, ABB, CH; Silvio Colombi, ABB Industrial Solutions, CH;  
Ivan Furlan, University of Applied Sciences and Arts of Southern Switzerland, CH

**036**                    **Sensorless Control and Synchronization for Solid-State Transformers Based on Active Unity Power Factor Modules**  
Francisco Freijedo, Miroljub Bakic, Thiwanka Wijekoon, Diego Lopez, Huawei Technologies, D

## Behavior and Reliability of SiC Devices

**037**                    **Characterization of 3.3 kV Discrete SiC MOSFETs in Synchronous Rectification Mode for PV Current Source Inverter Applications**  
Louis-Alexis Gomez, Luis Gabriel Alves Rodrigues, CEA Tech, F; Sébastien Sanchez, Guillaume Gateau, University of Toulouse, F

**038**                    **Influence of Turn-Off Gate-Voltage Undershoots on the Turn-On Behavior of SiC MOSFETs**  
Andreas Hürner, Paul Sochor, Rudolf Elpelt, Maximilian Wolfgang Feil, Qing Sun, Infineon Technologies, D

**039**                    **Transfer IV and Threshold Voltage Drift of GaN and SiC Cascode Discrete Devices Under Gate Bias Stress**  
Yasin Gunaydin, Saeed Jahdi, Xibo Yuan, Phil Mellor, Bernard Stark, University of Bristol, GB; Erfan Bashar, Olayiwola Aletise, Jose Ortiz Gonzalez, University of Warwick, GB

**040**                    **Power Cycling SiC MOSFETs: Study on Threshold Voltage Behavior and Solder-Void Decrease**  
Elena Mengotti, Helton Goncalves de Medeiros, Enea Bianda, David Baumann, Gerd Schlottig, ABB, CH; Joni Jormanainen, Jonny Ingman, ABB Drives, FIN; Roman Furrer, Bastian Rheingans, Empa, CH; Ulrike Grossner, Shweta Tiwari, Thomas Ziemann, ETH Zurich, CH

**041**                    **Improving the VF-IR Trade-Off in 650-V/1200-V SiC SBD by Development of Schottky Metal and Optimization of Device Structure**  
Kei Tanihira, Yoichi Hori, Yoko Yamamoto, Yuto Adachi, Takahiro Ogata, Shunsuke Asaba, Masakazu Kobayashi, Hiroshi Kono, Hideki Hayakawa, Akihiro Tsuyuguchi, Toshiba Electronic Devices & Storage, J; Georges Tchouangue, Toshiba Electronic Europe, D

## Renewable Energy Systems and Optimization

- 042**                    **Investigation of Innovative Cooling Systems for a Direct Driven Lightweight PMSG for Wind Power Applications**  
Jonas Steffen, Sebastian Lengsfeld, Axel Seibel, Fraunhofer Institute IEE, D; Klaus Schleicher, Mercedes Herranz Gracia, Aristide Spagnolo, Markus Klöpzig, Siemens, D; Joachim Krämer, Krämer Energietechnik, D
- 043**                    **Performance Evaluation of SiC MOSFETs for Isolated DC-DC Conversion in Medium Voltage Photovoltaic Power Plants**  
Minh Nhut Ngo, Jérémy Martin, Anthony Bier, CEA, F; Philippe Ladoux, University of Toulouse, F; Sébastien Sanchez, Icam, F
- 044**                    **Reliability of Inverters in Photovoltaic Power Systems – A Detailed Field Data Analysis**  
Felix Kulenkampff, Sebastian Franz, Klaus Kiefer, Lennart Sans, Fraunhofer Institute ISE, D
- 045**                    **Ideal Transformer Method Optimization for Power Hardware-in-the-Loop Simulations of Grid Connected Inverters**  
Marija Stevic, Ravinder Venugopal, OPAL-RT, D; Gayathri Tanuku, Amit Kumar KS, Jean-Nicolas Paquin, Syed Ahmed Raza Naqvi, OPAL-RT, CDN
- 046**                    **Influence of Link Capacitor Outsourcing and Reduction of Capacitors in DC fed Drive Inverters**  
Simon Puls, Lenze, D; Holger Borchering, Jan-Niklas Koch, Slavi Warkentin, University of Applied Sciences and Arts Ostwestfalen-Lippe, D

## Advanced Gate Drivers

- 047**                    **SOFTGATE – An IGCT Gate Unit for Soft-Switching**  
Jakub Kucka, Drazen Dujic, Power Electronics Laboratory, EPFL, CH
- 048**                    **A Self-Regulating Gate Control Based on the Parasitic Turn-On Effect for Low Losses and Low EMI of SiC MOSFET**  
Zheming Li, Mark-M. Bakran, Robert Maier, Michael Walter, University of Bayreuth, D
- 049**                    **An Improved Monitoring of Gate Leakage Current on SiC Power MOSFETs using Source Driver Topology**  
Antoine Laspeyres, Loreine Makki, Anne-Sophie Descamps, Christophe Batard, Corentin Darbas, Nicolas Ginot, University of Nantes, F; Stéphane Azzopardi, Thanh Long Le, Toni Youssef, Safran, F
- 050**                    **Real-Time Adjustable Voltage-Source Gate Driver with Resistance Emulation for Automated SiC MOSFET Characterization**  
Helge Wurst, Thomas Blank, Karlsruhe Institute of Technology, D; Bao Ngoc An, Schaeffler Automotive, D

- 051**                    **Use of an NSGA-II Genetic Algorithm and Active Gate Driving to Improve Simulated GaN Power Electronic Switching Waveforms**  
Sergejs Leonovs, Harry Dymond, Saeed Jahdi, Bernard Stark, University of Bristol, GB

### Passive Components

- 052**                    **Layer-by-Layer Printed Dielectrics: Scalable Nanocomposite Capacitor Fabrication for the Green Transition**  
William Greenbank, Thomas Ebel, Jacek Fiutowski, Prince Gupta, University of Southern Denmark, DK
- 053**                    **Trans-Inductor Voltage Regulator (TLVR): Circuit Operation, Power Magnetic Construction, Efficiency and Cost Trade-offs**  
Shreyankh Krishnamurthy, Pulse Electronics, D; David Wiest; Pulse Electronics, USA; Yosef Zhou, Pulse Electronics, CHN
- 054**                    **Optimization of Magnetic Components for an ACQR Flyback: Characterizations, Simulations, Manufacturing**  
Cédric Colonna, Thomas Harmand, 3D PLUS, F; Patrick Dubus, POWERLOGY, F
- 055**                    **Sizing Compact Transformers with Integrated Serial Inductance Suitable for a 1 MHz DC/DC LLC Converter**  
Ulrich Soupremanien, Marc Bohnke, Gerard Delette, CEA-Liten, F; Pierre Demumieux, CEA, F; Pierre Perichon, CEA-Leti, F; Samuel Marek-Favarel, Capgemini Engineering, F; Thierry Sutto, Exagan, F
- 056**                    **Novel Developments in Magnetics that Enable the High-Power High Frequency Power Conversion**  
Kapila Warnakulasuriya, Murata Power Solutions, GB

### Measurement Techniques and EMC

- 057**                    **Highly Dynamic Power Estimation and Efficiency Mapping Based on the Inverter's Switching Cycle as Averaging Interval**  
Alexander Stock, Hottinger Brüel & Kjaer, D
- 058**                    **Analysis of Fixture Design for Impedance Characterization of Multi-Chip Power Modules**  
Brian DeBoi, Andrew Lemmon, Chris New, University of Alabama, USA
- 059**                    **Common Mode of Inverters: Survey and Study of Filter Placement on Grid and Load Side**  
Benedikt Kohlhepp, Thomas Dürbaum, Daniel Kübrich, Julian Dobusch, Friedrich-Alexander-University Erlangen-Nuremberg, D
- 060**                    **Special Effects of Junction Temperature Measurement Based on the Internal Gate Resistance**  
Michael Gleissner, Mark-M. Bakran, University of Bayreuth, D

- 061**                    **High Bandwidth Solenoidal PCB Rogowski Coil**  
Tianqi Zhang, Luke Shillaber, Teng Long, University of Cambridge, GB

### Power Module Technology

- 062**                    **Fabrication of a Double-Sided Cooled Half-Bridge Silicon Carbide Power Module for Electric Vehicles**  
Riya Paul, Rayna Alizadeh, Ahmed Rahouma, Homer Alan Mantooth, University of Arkansas at Fayetteville, USA
- 063**                    **Impact of Technical Cleanliness on HV Automotive Applications**  
Michael Schleicher, Nesrine Damak, Semikron Elektronik, D
- 064**                    **The 7th Generation “X Series” Intelligent Power Module and Its Control IC Technology**  
Massimo Caprioli, Fuji Electric, I; Yuki Kumazawa, Takahiro Mori, Kaname Mitsuzuka, Kenichiro Satou, Kiyoshi Sekigawa, Yasuyuki Kobayashi, Fuji Electric, J

### Sintering Technologies

- 065**                    **Bonding Properties and Reliability Evaluation of Cu Paste in Low Temperature Pressureless Sintering**  
Shinichi Yamauchi, Kei Anai, Takashi Hattori, Satoshi Konno, Mitsui Mining & Smelting, J
- 066**                    **Bonding Between a Ceramic Wiring Board and Cooling Plate Using Copper Sintering Paste**  
Hideo Nakako, Michiko Natori, Dai Ishikawa, Yoshinori Ejiri, Showa Denko Materials, J; Kazuhiko Minami, Seiji Matsushima, Showa Denko, J
- 067**                    **Characterization of Sinter Materials and Processes by Scratch Test**  
Nicolas Heuck, Christian Thomas, Marcel Lawniczak, Michael Curkin, Hamm-Lippstadt University of Applied Sciences, D; Kurt-Georg Besendörfer, Pavel Vozdecky, SEMIKRON Elektronik, D

### System Reliability

- 068**                    **Estimating Auxiliary Power Supply Consumption of the Modular Multilevel Converter Submodule for the Condition Health Monitoring**  
Ignacio Polanco Lobos, Drazen Dujic, Power Electronics Laboratory, EPFL, CH
- 069**                    **System Consideration for Large Copper Wire and Ribbon Bonding in Mass Production**  
Tao Xu, Omid Niayesh, Jason Fu, Raymond Chen, Cristian Cionea, Kulicke & Soffa Industries, USA



- 070**                    **Fault-Tolerant Operation Algorithm for a Multi-Phase DC Converter with Coupled Inductors**  
Arturs Bogdanovs, Oskars Krievs, Riga Technical University, LV; Johannes Pforr, University of Applied Sciences Ingolstadt, D

#### GaN Switches in Mission Critical Applications

- 071**                    **Design and Characterization of an Interleaved GaN Half-Bridge IC with Matrix Layout for 48 V Applications**  
Richard Reiner, Michael Mikulla, Patrick Waltereit, Michael Basler, Stefan Mönch, Rüdiger Quay, Fouad Benkhelifa, Fraunhofer Institute IAF, D
- 072**                    **Experimental Evaluation of Dead Time Reverse Conduction Losses in Motor Drives Applications**  
Marco Palma, Efficient Power Conversion (EPC), I; Vincenzo Barba, Fabio Mandrile, Salvatore Musumeci, Polytechnic University of Turin, I
- 073**                    **All-Copper-Package (ACP) High-Power GaN HEMT Module Platform for xEV Traction Inverter and High-Speed DC Charger**  
Kongjing Li, Yangang Wang, Muhammad Morshed, Dynex Semiconductor, GB

#### Low Power Converters using WBG Materials

- 074**                    **Minimum Loss Operation of the Synchronous Buck Converter Using Si, SiC, and GaN Transistors**  
Reinhold Elferich, Christian Hattrup, Signify, NL
- 075**                    **ZVS Solutions for Flyback Topology and the Impact of GaN Utilization**  
Ionel Dan Jitaru, Rompower, USA; Constantin Radoi, Polytechnic Institute of Bucharest, RO
- 076**                    **Analysis of Interleaved Series Capacitor Tapped Buck Topologies for Adjustable Output Voltage Range**  
Alberto Otero Olavarrieta, Iñigo Martínez de Alegría, Estefanía Planas, Asier Matallana, Edorta Ibarra, University of the Basque Country, E

#### SiC Devices

- 077**                    **650-V and 1200-V SiC MOSFETs with Low RonA and Strong Reduction in Switching Losses**  
Masaru Furukawa, Toshiba Electronic Devices & Storage, J; Georges Tchouangue, Toshiba Electronics Europe, D; Yasuhiro Shimizu, Katsuhisa Tanaka, Kotani Yosuke, Masakazu Kobayashi, Hiroshi Kono, Hideki Hayakawa, Akihiro Tsuyuguchi, Toshiba, J

- 078**                    **High Temperature Performance of Next Generation 1200V SiC MOSFET die with Advanced Packaging Technology**  
Amy Romero, Adam Barkley, Jeffrey Casady, Satyavrat Laud, Anri Mikirtichev, Wolfspeed, USA; Dieter Liesabeths, Wolfspeed, D; Christophe Féry, Stefan Gunst, Andreas Hinrich, Sven Thomas, Heraeus, D; Habib Mustain, Heraeus, USA
- 079**                    **Dynamic Characteristics and SOA of the RoadPak SiC Module at Multiple Operating Conditions**  
Athanasios Mesemanolis, Tobias Keller, Milad Maleki, Hitachi Energy, CH
- 080**                    **3.3kV All SiC Module with 2nd Generation Trench Gate SiC MOSFETs for Traction Inverters**  
Yusuke Sekino, Sayaka Yamamoto, Yasuyuki Kobayashi, Takashi Shiigi, Hiroshi Kimura, Yuichi Onozawa, Takafumi Uchida, Keiji Okumura, Yoshiyuki Kusunoki, Susumu Iwamoto, Fuji Electric, J, Steffen Ewald, Fuji Electric, D
- 081**                    **Proven Power Cycling Reliability of SmartSiC™ Substrate for Power Devices**  
Eric Guiot, Gonzalo Picun, Frédéric Allibert, Alexis Drouin, Walter Schwarzenbach, Jean-Marc Bethoux, Séverin Rouchier, SOITEC, F; Jürgen Leib, Tom Becker, Tobias Erlbacher, Fraunhofer Institute IISB, D; Julie Widiez, CEA, F

## Reliability

- 082**                    **3.3kV 800A Next High Power Density Dual Si IGBT Module with High Power Cycle Durability**  
Taiga Arai, Kanta Makabe, Tsubasa Moritsuka, Isamu Yoshida, Akitoyo Konno, Koji Sasaki, Toshihito Tabata, Akiyoshi Tadano, Kan Yasui, Katsuaki Saito, Daisuke Kawase, Takayuki Kushima, Hitachi Power Semiconductor Device, J; Tomoyasu Furukawa, Hitachi, J
- 083**                    **Enhancing Voltage Rating of Standard Power Modules for Harsh Environment Applications**  
Hugo Reynes, Martin Guillet, SuperGrid Institute, F; Cyril Buttay, Eric Vagnon, University of Lyon, F
- 084**                    **Silver Sintering on PCBs – Methods and Reliability**  
Fabian Dresel, Jonas Müller, Jürgen Leib, Andreas Schletz, Fraunhofer Institute IISB, D
- 085**                    **On Superior Power Cycling capability of a High Power Density SiC Power Module for eMobility Application**  
Biwei Zhang, Antoni Ruiz, Milad Maleki, Hitachi Energy, CH
- 086**                    **Consequences of Temperature Imbalance for the Interpretation of Virtual Junction Temperature Provided by the VCE(T)-Method**  
Fabian Nehr, Uwe Scheuermann, SEMIKRON Elektronik, D

## Converter Design

- 087**                    **Designing the ANPC Inverter to Increase the Starting Torque in Traction Applications**  
Johannes Häring, Mark-M. Bakran, University of Bayreuth, D; Wolfgang Wondrak, Maximilian Hepp, Mercedes-Benz, D
- 088**                    **Design and Demonstration of A 75kW Grid-Tied Inverter Using Low-Inductance 1.7kV Silicon Carbide Modules**  
Yue Zhao, Fei Diao, Yuheng Wu, University of Arkansas, USA; Serge Bontemps, Microchip Technology, F; Avinash Kashyap, Microchip Technology, USA
- 089**                    **Self-Powered Synchronous Rectifying Active Bridge Compatible with Diode Bridge for Commercial Rectification**  
Yoshihiro Miwa, Hiroyuki Shoji, Hitachi, J; Takahiro Higuchi, Junichi Sakano, Tomoyuki Utsumi, Hitachi Power Semiconductor Device, J
- 090**                    **High Voltage Power Supply for Industrial X-Ray Application**  
Serge Gavin, Simon Kissling, Mauro Carpita, University of Applied Sciences and Arts Western Switzerland, CH; Marco Fontana, Alexandre Bapst, Thermo Fisher Scientific, CH
- 091**                    **Highly Efficient PFC Topology Using Constant Power Control Enabling Higher Power Density and Cost Savings in Passives**  
David Chilachava, Vincotech, D; Ernő Temesi, Marton Vazsonyi, Gabor Ipach, Vincotech, H

## Motors and Electric Drives

- 092**                    **Comparative Evaluation of Four-Pole Planetary Motor Variants**  
Andreas Brunner, Manfred Schrödl, Richard Spießberger, Technical University of Vienna, A
- 093**                    **Scalable Axial Flux Permanent Magnet Synchronous Machine for a Gearless In-Wheel Drive**  
Vanessa Linda Claus, Tankred Müller, Christian Rudolph, Hamburg University of Applied Sciences, D
- 094**                    **Comparison of Losses in Permanent Magnet Synchronous Machines fed with 2-level- or 3-level-NPC Converter**  
Tobias Knapp, Wilfried Hofmann, Ludwig Schlegel, Technical University of Dresden, D
- 095**                    **Synchronized MPTC Scheme for High Frequency PMSM Drives Using Dynamic Weighting Factor Calculation**  
Kristóf Gábor Bándy, Péter Pál Stumpf, Tóth-Katona Tamás, Budapest University of Technology and Economics, H
- 096**                    **Modular System Architecture for Large Multi-Axis Motion Control Systems in Automation**  
Timo Wilkening, Jens Onno Krah, Joschka Randerath, Miguel Avendano, Cologne University of Applied Sciences, D; Joachim Holtz, University of Wuppertal, D

### Thermal Management

- 097**      **Direct-Liquid-Cooled Next High Power Density Dual (nHPD2) Using Copper Base Plate**  
Hitoshi Nishimori, Norio Nakazato, Hitachi, J; Katsuaki Saito, Takayuki Kushima, Kouji Sasaki, Hitachi Power Semiconductor Device, J
- 98**      **A Reliability Study of Phase Change Thermal Interface Materials for Power Semiconductor Modules**  
Anwasha Fernandes, Yangang Wang, Muhammad Morshed, Robin Simpson, Dynex Semiconductor, GB
- 99**      **ShowerPower 3D - Highest Power Density for Future Generation of SiC Power Modules**  
Henning Ströbel-Maier, Fabio Carastro, Alexander Streibel, Klaus Kristen Olesen, Danfoss Silicon Power, D
- 100**      **New Dimensions in Lock-In Thermography for Failure Classification in Electronics with New Thermographic Cameras in HD Resolution**  
Marco Liepelt, Steffen Sturm, InfraTec, D

### Design and Optimization



- 101**      **Design Optimization of a MW-level Medium Frequency Transformer**  
Nikolina Djekanovic, Drazen Dujic, Power Electronics Laboratory, EPFL, CH
- 102**      **Over Voltage due to Cable Reflections at SiC Converters - Basic Effects and Countermeasures**  
Simon Johannliemke, David Reiff, Volker Staudt, Ruhr-University of Bochum, D
- 103**      **An Open-Source FEM Magnetics Toolbox for Power Electronic Magnetic Components**  
Nikolas Förster, Till Piepenbrock, Philipp Rehlaender, Oliver Wallscheid, Frank Schafmeister, Joachim Böcker, Paderborn University, D
- 104**      **Towards Digital Twins for the Optimization of Power Electronic Switching Cells with Discrete SiC Power MOSFETs**  
Salvatore Race, Ivana Kovacevic-Badstuebner, Michel Nagel, Thomas Ziemann, Ulrike Grossner, ETH Zurich, CH



### Wireless Power Transfer

- 105**      **Inductive Power Transfer System for Auxiliary Power Supply in Medium Voltage Converters**  
Xiaotong Du, Chengmin Li, Drazen Dujic, Power Electronics Laboratory, EPFL, CH
- 106**      **Optimization of a 2 MHz 500 W Compact Wireless Power Transfer System with a Large Voltage Conversion Ratio**  
Tim Krigar, Martin Pfost, TU Dortmund University, D

**107**                    **ZVS Class E2 Wireless Power Transfer System with Self-Resonant Transmission Coils for the Biomedical Application**  
Hannes Schwan, Gordon Elger, Johannes Pforr, University of Applied Sciences Ingolstadt, D

**108**                    **Method to Increase WPTS Robustness to Frequency Splitting and Bifurcation Phenomena**  
Damien Lemaitre, Benoit Sarrazin, Thierry Brincourt, Alexis Derbey, G2Elab, F; Yohan Wanderoid, Yves Lembeye, EDF, F

### SiC Modules, Characteristics and Applications

**109**                    **Challenges of Paralleling 3.3 kV SiC MOSFET Modules in HVDC Converter Submodules**  
Lukas Bergmann, Mark-M. Bakran, University of Bayreuth, D; Marcus Wahle, Siemens, D

**110**                    **Experimental Study on Turn-off Process of Medium Voltage SiC MOSFET Modules**  
Jacek Rabkowski, Mariusz Zdanowski, Warsaw University of Technology, PL; Fernando Gonzalez-Hernando, Irma Villar, Ikerlan Technology Research Centre, E; Uxue Larrañaga, CAF POWER & AUTOMATION, E

**111**                    **Short-Circuit Protection of a Power Module with Trench-SiC-MOSFET. Can DESAT be Fast Enough?**  
Vikneswaran Thayumanasamy, Kevin Lenz, Carlos Fuentes, ROHM Semiconductor, D; Ingo Rabl, Jürgen Engstler, SEMIKRON Elektronik, D

**112**                    **Full SiC Phase-leg Power Module for Airborne DC/AC Power Conversion Applications**  
Thomas Guillemet, Sébastien Oge, Solenne Hameau, Timothée Frappé, Sylvie Loiseau, Richard Morisse, Thales DMS, F

**113**                    **Experimental Evaluation of a SiC MOSFET in Surface Mount Power Device Package**  
MD Rishad Ahmed, Ahmed Topkil, Qinlong Chen, University of Nottingham, GB

**114**                    **Comparison of Dissipation Loss Reduction Rates of 1.2kV and 1.7kV All-SiC Modules Against Si-IGBT Module for PWM Inverters**  
Ben Bradel, Fuji Electric, D; Susumu Iwamoto, Aiko Takasaki, Takafumi Uchida, Makoto Isozaki, Yoshiyuki Kusunoki, Yasuyuki Kobayashi, Fuji Electric, J;

**115**                    **Using a 4-leg Three Phase Inverter to Connect the AC Grid with a Bipolar DC Grid**  
Peter van Duijsen, Casper Grootes, Diego Zuidervliet, The Hague University of Applied Sciences, NL

### Power Module Reliability

- 116**                    **Influence of Magnetic Coupling Effects between Load and Gate Commutation Loop on the Short Circuit Behavior**  
Christian Bäumlér, Thomas Basler, Tobias Konstantin Vogel, Bo Zhang, Chemnitz University of Technology, D
- 117**                    **Over Temperature Protection of Power Module under Electric Water Pump Failure Condition in EV**  
JeHwan Lee, YoungJoo Ko, SungMin Lee, JungHong Joo, SangChul Shin, Hyundai Motor, ROK
- 118**                    **Extend Power Density and Lifetime of Latest SiC and 7th Gen IGBT Power Module thru Transfer Molded Technology**  
Jonathan Harper, Jinchang Zhou, ON Semiconductor, USA; Chee Hiong Chew, ON Semiconductor, MAL; Joji Corbillon, Silnore Sabando, ON Semiconductor, VN
- 119**                    **Determination of Ideal Magnetic Sensor Arrangements for Health Monitoring of Power Electronic Modules**  
Haosu Huai, Juergen Wilde, Nasibeh Naserizaker, University of Freiburg, D; Michael Wolff, Gerd Griepentrog, Elena Ehret, Technical University of Darmstadt, D
- 120**                    **Impact of Thermal Cycling Frequency on IGBT Power Module Lifetime**  
Guillaume Pellecuer, Olivier Arnould, André Chrysochoos, François Forest, Jean-Jacques Huselstein, Thierry Martiré, University of Montpellier, F
- 121**                    **Detecting Soldering Quality in Power Modules with Zth in the Loading Phase**  
Hao Wang, Hans-Günter Eckel, Jan Fuhrmann, University of Rostock, D
- 122**                    **The Impact of Power Cycling Induced Degradation Mechanisms on the Magnetic Field Signature of IGBTs**  
Michael Wolff, Gerd Griepentrog, Technical University of Darmstadt, D

### Thermal Design

- 123**                    **Design Tool for Temperature Estimation on PCB**  
Bernd Schroeder, Bernd Stube, Technical University of Berlin, D; Olaf Mueller, AEconversion, D; Eckart Hoene, Stefan Hoffmann, Fraunhofer Institute IZM, D
- 124**                    **Thermal Analytical Modelling of the Heat Transfer Through a Power PCB Dedicated to a High Current Density Modular Converter**  
Gaël Pongnot, Fabien Adam, Denis Labrousse, Clement Mayet, Mickaël Petit, Marie-Christine Duluc, SATIE Laboratory, F
- 125**                    **Improving the Performance of DC-DC Converters by Using SMD Packages with Top-Side Cooling**  
Marco Papasero, Daniela Cavallaro, Cristiano Gianluca Stella, Domenico Nardo, Stefano Orlando, STMicroelectronics, I

**126**                    **Optimization of Thermal Performance of Top-Side Cooled Discrete Power Semiconductors**  
Severin Kampl, Stefan Vassilev Mollov, Infineon Technologies, A

**127**                    **Design of Thermal Management for Double-Sided Cooled SiC-Power Semiconductors**  
Simon Cepin, Holger Borcharding, University of Applied Sciences and Arts Ostwestfalen-Lippe, D; Ruediger Kusch, Christian Schnücker, Volkswagen Group Innovation, D; Adrian Lis, Infineon Technologies, D

### Advanced Si Devices

**128**                    **Usability of Three-Level ANPC Converters after Short-Circuit Failure**  
David Hammes, Nastaran Hammes, Sidney Gierschner, Hans-Günter Eckel, University of Rostock, D; Dietmar Krug, Siemens, D

**129**                    **3.3 kV IGBT4 and EC4 Technology with High Electrical Robustness for Current Density Increase in IHV B Modules**  
Evgeny Obzherin, Matthias Buerger, Jens Czichon, Infineon Technologies, D

**130**                    **A New Platform for High Power Phase Controlled Thyristors (PCT) and Rectifier Diodes**  
Nino Degiampietro, Chiara Corvasce, Christian Winter, Hitachi Energy, CH; Zuzana Ptáková, Hitachi Energy, CZ

**131**                    **The Relevance of Boundary Conduction Mode for High Pulse Power DC-DC Converters Using GCTs and IGCTs**  
Fabian Albrecht, Felix Haag, Klaus F. Hoffmann, Helmut-Schmidt-University, D; Volker Brommer, Oliver Liebfried, French-German Research Institute of Saint-Louis (ISL), F

**132**                    **10 kV Reverse-Conducting Integrated Gate-Commutated Thyristors for HVDC Power Transmission**  
Davin Guedon, Philippe Ladoux, University of Toulouse, F; Umamaheswara Reddy Vemulapati, Thomas Stiasny, Christian Winter, Hitachi Energy, CH; Sebastien Sanchez, Icam, F; Sebastien Cornet, EDF, F

**133**                    **Your 15 V Zener and TVS Diodes are Avalanche Diodes**  
Daniel Chatroux, CEA-Liten, F

### GaN Devices

**134**                    **Potential of GaN Semiconductors in Electric Vehicle Inverters**  
Maximilian Hepp, Leonhard Hertenstein, Alexander Nisch, Wolfgang Wondrak, Marcus Heller, Felix Bertele Mercedes-Benz, D

**135**                    **A Breakthrough Step in Power Conversion Design: 650V STI2GaN IC Family to Boost the DC-DC Converter Performance**  
Filippo Scrimizzi, Federica Cammarata, Nadia Lecci, Giuseppe Longo, STMicroelectronics, I

- 136**                    **Fast Switching of High Current WBG Power Devices**  
Edward Shelton, Dan Rogers, University of Oxford, GB; Lathom Louco, BorgWarner, USA; Jeff Carter, BorgWarner, GB; Mike Beadman, Cambridge Design Partnership, GB; Patrick Palmer, Simon Fraser University, CDN
- 137**                    **Re-inventing Power Electronics: NexGen Power Systems with Vertical GaN™**  
Dinesh Ramanathan, NexGen Power Systems, USA
- 138**                    **Precise Determination of Dynamic RDSon in AlGaIn/GaN Power HEMTs under Soft Switching Condition**  
Maximilian Goller, Thomas Basler, Josef Lutz, Nick Thönelt, Christian Schwabe, Gengqi Li, Chemnitz University of Technology, D

## Packaging I

- 139**                    **Innovative and Integrated Production Technology Allows Effective Packaging**  
Benjamin Hertweck, Heiko Müller, KERN-LIEBERS, D; Andreas Altmann, psm protech, D
- 140**                    **First 650V 60A GaN Power Module in a Compact SP1 Package**  
Pierre-Laurent Doumergue, Serge Bontemps, Microchip Technology, F
- 142**                    **First Aerospace Qualified Baseless SiC Power Module Family Improves High Reliability Systems Efficiency**  
Alain Calmels, Serge Bontemps, Pierre-Laurent Doumergue, Edouard Petrequin, Maxime Barrière, Microchip Technology, F; Shane O`Donnell, Bernard McAvinue, Vincent Walsh, Microchip Technology, IRL
- 143**                    **Ultra-Compact Automotive Power Module for 100 kW xEV Application**  
Shinichiro Adachi, Tomoyuki Obata, Nobuhide Arai, Nobuhiro Higashi, Yoshihiro Tateishi, Fuji Electric, J
- 144**                    **Reflow Soldering of TO-247PLUS Discrete Package in Commercial, Construction and Agricultural Vehicle Application**  
Omar Harmon, Lukas Hein, Infineon Technologies, A; Zhenbo Zhao, Infineon Technologies Center of Competence, CHN
- 145**                    **HV LinPak, High Voltage Half Bridge IGBT Power Module with Balanced Switching Behavior for Easy Paralleling**  
Roman Ehrbar, Andreas Rösch, Gontran Pâques, Antoni Ruiz, Wolfgang Amadeus Vitale, Andreas Baschnagel, Vinoth Sundaramoorthy, Fabian Fischer, Virgiliu Botan, Hitachi Energy, CH; Giovanni Antonio Salvatore, University of Venice, I
- 146**                    **Additive Manufacturing in Electronics – Filament Overview and Special Focus on Carbon Black Filament Properties Investigation**  
Andre Schuhl, Ulf Schwalbe, Katharina J. Schiffhauer, Emanuel Lemnitz, Fulda University of Applied Sciences, D



## SiC Devices

- 147**      **A 3.6kV Multi-Level SiC MOSFET Power Module with 3D Integrated Driver and Passive Components for Pulsed Load Applications**  
Frank Hoeven, Paul Ervine, Thomas Gerrits, Joost van Straalen, Lars Peters, Prodrive Technologies, NL
- 148**      **Threshold Voltage Drift and On-Resistance of SiC Symmetrical and Asymmetrical Double-trench MOSFETs Under Gate Bias Stress**  
Juefei Yang, Saeed Jahdi, Bernard Stark, Phil Mellor, University of Bristol, GB; Ruizhu Wu, Olayiwola Alatise, Jose Ortiz-Gonzalez, University of Warwick, GB
- 149**      **Performance Evaluation of SiC MOSFET-Based Half-Bridge Converters Under Dynamic Voltage Clamp Limits**  
Luciano Salvo, Mario Pulvirenti, Fabio Occhipinti, Angelo Sciacca, Massimo Nania, Gionatan Montoro, STMicroelectronics, I
- 150**      **1.2 kV Trench IGBT with SiC JBS Diode for High Frequency Switching Applications**  
Nick Schneider, Elizabeth Buitrago, Yulieth Arango, Nicolo Oliva, Toni Ruiz, Luca De Michielis, Lars Knoll, Gontran Pâques, Hitachi Energy, CH
- 151**      **Analytical Circuit Model for Coss Losses in SiC Junction Termination Extensions**  
Jia Zhuang, Zikang Tong, Juan Rivas, Stanford University, USA; James Victory, Alexander Bolotnikov, Kan Jia, ON Semiconductor, USA; Jaume Roig, ON Semiconductor, B
- 152**      **Research of SiO<sub>2</sub> Thin Film Deposition by PECVD in SiC Power Device Manufacturing**  
Songlin Yang, Yangang Wang, Kongjing Li, Dynex Semiconductor, GB; Chengzhan Li, Haihui Luo, Zhuzhou CRRC Times Semiconductor, CHN
- 153**      **Understanding the Switching Behavior of Fast SiC MOSFETs**  
Paul Sochor, Andreas Huerner, Qing Sun, Rudolf Elpelt, Infineon Technologies, D
- 154**      **Efficient and Robust 750V SiC MOSFETs for Electric Vehicles**  
Ranbir Singh, Sumit Jadav, Siddarth Sundaresan, Jaehoon Park, Vamsi Mulpuri, GeneSiC Semiconductor, USA

## Measurement Methods

- 155**      **Modular Dynamic Characterization Bench for Wide Bandgap Power Semiconductors**  
Sergio Jimenez, Andrew Lemmon, Christopher New, University of Alabama, USA; Blake Nelson, Wolfspeed, USA
- 156**      **Static and Dynamic Measurements for GaN Integrated Switches**  
Dominique Bergogne, Grégory Calabro, Srivathsan Hariharan, Cédric Reymond, Thanh Hai Phung, Sebastian Gaviria-Duque, Plinio Bau, Johan Delaine, Wise-Integration, F

- 157**                    **Noise Reduction in Open-Loop Hall-Effect-Based Current Sensing for Current-Controlled Three-Phase AC-DC Converters**  
Alexis Gómez, Francisco Azcondo, Alberto Pigazo, Christian Brañas, Rosario Casanueva, Francisco J. Díaz, University of Cantabria, E
- 158**                    **Assessment of State-of-the-Art Current Sensors for Fast Switching**  
Florian Wilhelmi, Andreas Schmid, ZF Friedrichshafen, D; Andreas Lindemann, Otto-von-Guericke-University, D
- 159**                    **Advantages of Rogowski Coil over Desaturation Method for Leg Short Circuit Detection in Inverters**  
Ali Mutlu, Akim Metal, TR; Bahaeddin Avni Kürüm, Turkish-German University, TR; Deniz Yildirim, Istanbul Technical University, TR
- 160**                    **Wireless Position Sensor to Determine the Wind Turbine Blade Tip Clearance for Higher Efficiency and New Wind Turbines**  
Wilke Philipps, Henning Sauerland, Holger Groke, Bernd Orlik, University of Bremen, D; Michael Beyer, Marcel Krüger, Windrad Engineering, D
- 161**                    **Minimization of a VSD Multilevel Inverter Output Filter through a Systemic Modeling Approach**  
Marcelo Lobo Heldwein, Technical University of Munich, D; Lucio Steckling, WEG Drives and Controls, BR

### Advanced Packaging and Reliability

- 162**                    **A Review of Short Circuit Performance in 650 V Power Devices: SiC MOSFETs, Silicon Super-Junction MOSFETs, SiC Cascode JFETs, Silicon MOSFETs and Silicon IGBTs**  
Jose Ortiz Gonzalez, Erfan Bashar, Nereus Agbo, Ruizhu Wu, Simon Mendy, Olayiwola Alatise, University of Warwick, GB; Saeed Jahdi, University of Bristol, GB; Gareth Davies, Andrew Withey, Jana Demitrova, Sam Evans, Nexperia Newport, GB; Mike Jennings, University of Swansea, GB
- 163**                    **Radiation Hardness of Si- and SiC-Power-MOSFETs in Particle Accelerator Environments**  
Milad Khani, Gerd Griepentrog, Technical University of Darmstadt, D; Ekaterina Kozlova, Alexey Sokolov, GSI Helmholtz Centre for Heavy Ion Research, D
- 164**                    **Impact of Forward-Recovery Losses on  $T_{vj}$ , Max and Lifetime in ANPC-Topology for Si IGBTs and Diodes**  
Alexander Philippou, Andressa Colvero Schittler, Ainhua Puyadena Mier, Christian Müller, Franz-Josef Niedernostheide, Infineon Technologies, D
- 165**                    **Overvoltage Transients in Wide Bandgap-Based Inverter-Fed Variable Speed Electrical Drives**  
Svetomir Stevic, Kay Hameyer, Andreas Thul, Maximilian Lauerburg, Yusa Tombul, RWTH Aachen University, D
- 166**                    **Improving the Power Efficiency of Welding Machines Using 1200 V CoolSiC MOSFET Discrete with .XT Interconnection Technology**  
Jorge Cerezo, Infineon Technologies, A

- 167**                    **Design Tool for Rapid 3D Modelling of SiC Power Modules and Simulation of Parasitic Inductances with Experimental Verification**  
Christoph Lüdecke, Rik W. De Doncker, Jonas Winkelhake, RWTH Aachen University, D

**Design Tools**

- 168**                    **Extraction of Parasitic Elements of a Printed Circuit Board applied to a GaN Half-Bridge**  
Benedikt Kohlhepp, Thomas Dürbaum, Daniel Kübrich, Jeremias Kaiser, Samuel Faber, Friedrich-Alexander-University Erlangen-Nuremberg, D
- 169**                    **A Novel Analytical Time-Domain Calculation Method for the Weighted Total Harmonic Distortion (WTHD) in PWM Inverters**  
Panagiotis Mantzanas, Thomas Dürbaum, Friedrich-Alexander-University Erlangen-Nuremberg, D
- 170**                    **Investigation on Blanking Time Effects Regarding Cross Currents in Time-Staggered Switching Mode**  
David Reiff, Simon Johannliemke, Volker Staudt, Ruhr-University of Bochum, D
- 171**                    **A High-Speed and High-Accuracy Power Device Waveform Simulation Method**  
Felipe Filsecker, ROHM Semiconductor, D; Makoto Murata, Asuma Imamura, Shimpei Fujita, Naotaka Kuroda, Yohei Nakamura, Atsushi Yamaguchi, ROHM, J
- 172**                    **Flexible and Cost-Effective HiL System for Module-Based VSC Simulation - Part I: Fundamental System Architecture and Operation**  
Julian Lange, Tobias Barth, Benjamin Hinrichs, Siemens Energy Global, D
- 173**                    **Flexible and Cost-Effective HiL System for Module-Based VSC Simulation - Part II: A Fast and Tunable FPGA Based Circuit Simulation Model**  
Tobias Barth, Julian Lange, Siemens Energy Global, D
- 174**                    **High-Fidelity Real-Time Simulation of Dual-Active Bridge Converters**  
Marija Stevic, Ravinder Venugopal, OPAL-RT, D
- 175**                    **Rapid Prototyping Framework for Integrated Modular Motor Drives: Modelling, Simulation and Automated Code Generation**  
Lukas Wild, Martin Schiestl, Maurizio Incurvati, Ronald Stärz, MCI The Entrepreneurial University, A
- 176**                    **Thermal Modeling of PCB Magnetic Components Based on Finite Element 2D Thermal Networks**  
Lucia Clavero Ordonez, Mirosljub Bakic, Thiwanka Wijekoon, Huawei Technologies, D; Pedro Alou Cervera, Alberto Delgado Expósito, UPM, E

## Power Converters: Design and Control Method Optimization

- 177 **High-Pass Design in Active Filter Damping**  
Sabrina Ulmer, Gernot Schullerus, Ertugrul Sönmez, Reutlingen University, D
- 178 **Reduced Order Modelling for Solid-State Transformers Based on Active Unity Power Factor Modules**  
Francisco Freijedo, Alvaro Rubinos Sicre, Miroljub Bakic, Thiwanka Wijekoon, Mauro Valente, Huawei Technologies, D
- 179 **Analysis and Control of Active Ripple Energy Storage for Single-Phase PFC Converters**  
Alex Rossi, Alessandro Pevere, Infineon Technologies, A; Roberto Petrella, University of Udine, I
- 180 **Low-Cost Microcontroller Based Implementation of Finite Control State Model Predictive Control for Front-End Power Converters**  
Giuseppe Aiello, Francesco Gennaro, Filiberto Mancuso, Vincenzo Mormina, STMicroelectronics, I; Giacomo Scelba, Mario Cacciato, Giovanni Antonio Muscato, University of Catania, I
- 181 **Quadratic Buck-Boost Single Switch Converter in Low Power SSL Applications: Pros and Cons Analysis**  
Matteo Sucameli, STMicroelectronics, I
- 182 **Extending Output Power of Unified AC Input Light Industrial Applications by SiC MOSFET**  
Simon Kim, Infineon Technologies, ROK; Kwok Wai Ma, Infineon Technologies, SGP
- 183 **Operation of a SiC-based Three-Phase PFC Converter in an Industrial DC Conductor System with Distributed DC Link Capacitors**  
Jan-Niklas Koch, Raphael Otte, Holger Borchering, University of Applied Sciences and Arts Ostwestfalen-Lippe, D
- 184 **An Automotive High-Frequency Coreless Transformer in 11kW Dual Active Bridge Converter**  
Valentin Rigot, Daniel Sadarnac, Jihen Sakly, VEDECOM Institute, F; Tanguy Phulpin, GeePs, F

## Control Methods

- 185 **Decentralized Control with Submodule Temperature Balancing for Modular Multilevel Converter**  
Le Nam Pham, Quoc Dung Phan, Ho Chi Minh City University of Technology, VN
- 186 **Current Limitation Methods during Grid Faults for Power Converters with Fictitious Synchronous Generator Control**  
Florian Redmann, Alexander Ernst, Bernd Orlik, University of Bremen, D
- 187 **Validation of a Converter Control Based on a Generator Model as Voltage Source**  
Alexander Ernst, Wilfried Holzke, Dawid Koczy, Bernd Orlik, University of Bremen, D

- 188      **Dual Active Bridge Converter: Simple Peak Current Limitation by Dual Phase Shift Control**  
Lukas Fräger, Niklas Badenhop, Dennis Kampen, Sascha Langfermann, Michael Owzareck, BLOCK Transformatoren-Elektronik, D; Jens Friebe, Leibniz University Hannover, D
- 189      **Multi-Objective Analysis of Pulse-Width Modulation Techniques for Five-Phase Inverters**  
Ander DeMarcos, Unai Ugalde, Jon Andreu, Markel Fernández, Edorta Ibarra, University of the Basque Country, E
- 190      **Robust Hysteresis Control for Full-Bridge LLC Resonant Converters Using an Isolated Measurement Scheme**  
Lukas Keuck, Joachim Böcker, Frank Schafmeister, Paderborn University, D
- 191      **Economical Implementation of Model Predictive Control for Minimization of Current and Torque Distortions in Induction Machines**  
Morris Fuller, Gerd Griepentrog, Haoran Wang, Technical University of Darmstadt, D; Oliver König, AVL LIST, A
- 192      **Software-Based Power Factor Correction by Using Iterative Learning Control for Battery Chargers with LLC Resonant Converter Topology**  
Alessio Cavaterra, Ulf Schwalbe, Steven Lambeck, Fulda University of Applied Sciences, D; Martin Wattenberg, Infineon Technologies, A

## Power Converters

- 193      **Comparison of Three-Level Grid-Forming Inverter Topologies for Unbalanced and Nonlinear Load Conditions in Microgrids**  
Daniel Stracke, Fabian Schnabel, Marco Jung, Sebastian Sprunck, Fraunhofer Institute IEE, D
- 194      **Solutions for Reducing and Controlling Voltage Unbalance in HERIC Inverters**  
Domenico Nardo, Simone Buonomo, Alfio Scuto, STMicroelectronics, I
- 195      **Hardware-in-the-Loop Development of a 30 kV / 100 kW / >150 kHz SiC-Based Resonant Converter**  
Tobias Strittmatter, Ishan Pendharkar, Marco Thommen, Nicola Schulz, University of Applied Sciences and Arts Northwestern Switzerland, CH
- 196      **Detailed Simulation and Efficiency Analysis of Deadtime Behavior in Dual Active Bridge DC-DC Converters**  
Manuel Häußermann, Heinrich Steinhart, Aalen University of Applied Sciences, D
- 197      **Design and Control of a 1 MHz DC-DC Soft-Switching LLC Converter with Wide Band Gap GaN Components**  
Emmanuel Marcault, Pierre Demumieux, Mathieu Gavelle, CEA, F; Pierre Perichon, CEA-Leti, F; Samuel Marek-Favarel, Capgemini Engineering, F; Thierry Sutto, STMicroelectronics, F

- 198**                    **SiC & GaN Comparison for High Switching Frequency, High Efficiency 7 kW Boost Converter**  
Florent Loiselay, Leyla Arioua Habarek, Joao Oliveira, Ali Ahousessein, VEDECOM Institute, F

### Power Supplies

- 199**                    **A Study on the Influence of the Transformer on Cross-Regulation in DCM Multi-Output Flybacks**  
Denis Motte-Michellon, Bruno Cogitore, Exxelia, F; Yves Lembeye, Brahim Ramdane, G2elab, F
- 200**                    **Modified  $d(2-d)/(1-d)^2$ -Converter**  
Helmut Votzi, Felix Himmelstoss, University of Applied Sciences Technikum Vienna, A
- 201**                    **High Frequency DCDC GaN HEMT USB Type-C PD EPR Four-Switch Buck-Boost Converter**  
Martin Schiestl, Andreas Albrecht, Ronald Stärz, Maurizio Incurvati, MCI The Entrepreneurial University, A; Manuel Hollfelder, Infineon Technologies, D
- 202**                    **High Efficiency Digital Centric DCDC with Low Complexity Analog Circuit**  
Lionel Cimaz, STMicroelectronics, F
- 203**                    **A Comparison among Wide Bandgap Devices using a CLLLC Bidirectional Resonant Converter**  
Alejandro Llop, Inigo Pena, Susana Apinaniz, Salvador Ceballos, Kepa Mendibil, Tecnalia Research, E
- 204**                    **Very Wide Input Voltage Converter with Custom Planar Magnetics Components for a Space Application**  
Cédric Colonna, 3D Plus, F; Denis Labrousse, ENS Cachan - SATIE, F; Patrick Dubus, POWERLOGY, F
- 205**                    **Grid-Tied ACDC Converters and Protection in the DC Grid**  
Peter van Duijsen, Diego Zuidervlie, The Hague University of Applied Sciences, NL

### Passive Components

- 206**                    **Study of Combined Solutions for Thermal Management and Electromagnetic Shielding: Shielding Cabinets, EMI Absorbers and Thermal Gap Fillers**  
Antonio Alcarria, Jorge Victoria, Victor Martinez, Sebastian Mirasol, Ivan Valcarcel Bustos, Antonio Agapito Tebar, Würth Elektronik eiSos, D; Adrian Suarez, Pedro Martínez, Jose Torres, University of Valencia, E
- 207**                    **Frequency and Temperature Dependence of the Electrical Resistivity of High Frequency MnZn Ferrites**  
Bernd Ackermann, Signify Research, NL; Herbert Jungwirth, Michael Schmidhuber, SUMIDA Components & Modules, D

- 208**            **A Smart Low-Cost Power Generator for Upcoming Isolation Material Stress Tests**  
Paul Aspalter, Hans Ertl, Technical University of Vienna, A; Markus Vogelsberger,  
Alstom Austria, A
- 209**            **K-TEM: Online Power Can Thermal Simulation Tool**  
Dario Zuffi, Massimiliano Abbenante, Walter Bruno, Evangelista Boni, Massimo Totaro,  
KEMET Electronics, I; Lachezar Zhivkov, KEMET Electronics, BG
- 210**            **New Generation Capacitor Films for 150°C High Voltage AC-DC Inverter Applications**  
Adel Bastawros, Matt Niemeyer, James Mahood, Andrew Pingitore, SABIC, USA;  
Fumio Yu, Takamune Sugawara, SABIC, J
- 211**            **Losses of Nanocrystalline Core Materials for High Power, High Frequency Applications**  
Jakob Vellinger, Simon Schramm, Daniel Goldmann, Munich University of Applied  
Sciences, D; Jörg Metzger, Inductron Inductive Electronic Components, D
- 212**            **A Simple SPICE Modeling Strategy for Common-Mode Chokes**  
Maurizio Tranchero, Paolo Santero, Ideas & Motion, I

#### Motor and Inductors

- 213**            **A Novel Single-Tooth Winding Induction Machine**  
Arthur Grün, Vlado Ostovic, HTW Saar University of Applied Sciences, D; Mario Pacas,  
University of Siegen, D
- 214**            **Investigation of Open-Loop Predictor Implementation Methods for Online Parameter Estimation of IPMSM**  
Aravinda Perera, Roy Nilsen, Thomas Haugan, Norwegian University of Science and  
Technology, N
- 215**            **Torque Control of Induction Machines Using QRM-MPC Approach**  
Kristóf Gábor Bándy, Péter Pál Stumpf, Budapest University of Technology and  
Economics, H
- 216**            **Parameter Sensitivity of MRAS-Based Sensorless Control for PMSM Considering Speed Accuracy and Dynamic Response at Low Stator Frequencies**  
Michael Brüns, Tankred Müller, Christian Rudolph, Hamburg University of Applied  
Sciences, D
- 217**            **I-F Start-Up Procedure of an Induction Machine with Smooth Transition to Sensorless Vector Control**  
Stefan Hüll, Jochen Staiger, Heinrich Steinhart, Swen Bosch, Aalen University of  
Applied Sciences, D
- 218**            **Knowledge-Based Engineering for System Optimization of Power Electronics including the Electric Motor Design**  
Max Kolletzki, Friedemann Ohl, Marco Denk, Brose Fahrzeugteile, D

- 219**                    **A Survey on Adjustable Inductances for Power Electronic Circuits**  
Sönke Brandt, Guido Schierle, Michael Meissner, Klaus F. Hoffmann, Noah Polap,  
Helmut-Schmidt-University, D
- 220**                    **Optimum Design of High Current Power Planar Inductors with Flat Winding**  
Todor Filchev, Himag Planar Magnetics, GB; Alex Van den Bossche, Ghent University,  
B

### Intelligent Gate Drives

- 221**                    **Hardware Development of an Active Gate Driver to Mitigate Oscillations of SiC MOSFET Switching Process**  
Michael Walter, Mark-M. Bakran, Robert Maier, Zheming Li, University of Bayreuth, D
- 222**                    **Advanced Overcurrent Detection with Digital Controllable Blanking Time for Fast SiC-Switch Protection**  
Bernhard Strzalkowski, Analog Devices, D
- 223**                    **Two-Level, Slew-Rate Control Reduces the Temperature Stress of Power Semiconductors in Power Modules**  
Wolfgang Frank, Michael Ebli, Niclas Thon, Infineon Technologies, D
- 224**                    **Design and Performance Assessment of a Digital Gate Driving Solution for Silicon Carbide Power Modules**  
Yue Zhao, Fei Diao, Yuheng Wu, University of Arkansas, USA; Rob Weber, Nitesh Sathesh, Avinash Kashyap, Microchip Technology, USA; Vipin Gaonkar, Microchip Technology, IND
- 225**                    **femtoCore: An Open Source Processor Architecture for Power Electronics Controls**  
Filippo Savi, Davide Barater, Giovanni Franceschini, University of Modena and Reggio Emilia, I; Giampaolo Buticchi, University of Nottingham, CHN
- 226**                    **Precision Gate Drive Featuring High Dead-Time Resolution for Soft Switched Converters**  
Martin Nießen, Georg Jöntgen, Christian Peter Dick, Cologne University of Applied Sciences, D
- 227**                    **Digitally Adjustable Gate Resistor Concept for Automated and Time-Saving Gate-Resistor Selection - Improvement by Reduction of Parasitic Inductances**  
Michael Meissner, Aaron Meyer Herrmann, Norman Landskron, Klaus F. Hoffmann, Helmut-Schmidt-University, D
- 228**                    **Evaluation of the Driving Characteristics of Electric Commercial Vehicles by the Use of Inertial Measurement Units**  
Mathias Herget, Ulf Schwalbe, Lukas Böhning, Fulda University of Applied Sciences, D



## Charging

- 229**                    **The Potential of SiC Semiconductors for High Power Electric Vehicle Charging Stations**  
Katharina Machtinger, Markus Makoschitz, AIT Austrian Institute of Technology, A
- 230**                    **AC and DC Charging for Electric Vehicles with a Battery Modular Multilevel Management (BM3) Converter System**  
Johannes Buberger, Julian Estaller, Wolfgang Grupp, Florian Schwitzgebel, Andreas Wiedenmann, Ali Mashayekh, Manuel Kuder, Richard Eckerle, Thomas Weyh, Universität der Bundeswehr München, D
- 231**                    **Efficiency Investigation of a Battery Modular Multilevel Management Converter System**  
Nina Sorokina, Julian Estaller, Manuel Kuder, Wolfgang Grupp, Anton Lesnicar, Richard Eckerle, Thomas Weyh, Universität der Bundeswehr München, D
- 232**                    **Direct Charging of Electric Vehicle Using Photovoltaic System with Minimum Power Loss**  
Martin Kröniger, Mohammad Vedadi, Otto Kreuzer, Fabian Weiß, Deggendorf Institute of Technology, D
- 233**                    **Analysis of Magnetic Flux Density in a Model of an Inductive-Resonance Energy Transfer System**  
Desislav Iliev, Nikolay Madzharov, Technical University of Gabrovo, BG
- 234**                    **The Resurrection of GTOs and Thyristors as Core Components in MW-Charger-Application and Railway/Mining Refurbishment**  
Martin Schulz, Daniel Hoffmann, Michael Ketterer, Littelfuse Europe, D
- 235**                    **Four-Leg EV Chargers for Grid Supporting**  
Antonio-Miguel Muñoz-Gómez, Ricardo Igea, Javier Ballestín Fuertes, Gregorio Fernandez, Daniel Marquina, Fundación Circe, E

## Transformers and Passive Components

- 236**                    **Mathematical Model of the Temperature Rise of a Wireless Power Transfer Coil in DC Operation**  
Christian Merz, Daniel Gückelhorn, Würth Elektronik eiSos, D; Cem Som, Würth Electronic Midcom EU, D
- 237**                    **Analysis of Decoupling Capacitor Effectiveness for Multi-Chip Power Modules**  
Christopher New, Brian DeBoi, Andrew Lemmon, University of Alabama, USA
- 238**                    **Wireless Power Transfer Losses Redefined by COG Capacitors**  
Damien Lemaitre, Benoît Sarrazin, Thierry Brincourt, Alexis Derbey, Yves Lembeye, G2elab, F; Yohan Wanderoild, EDF, F

- 239**                    **Class Phi2 Amplifier Using GaN HEMTs at 13.56MHz with Tuned Transformer for Wireless Power Transfer**  
Sabrina Ulmer, Klaus-Dieter Kächele, Kathrin Kocher, Ertugrul Sönmez, Gernot Schullerus, Reutlingen University, D
- 240**                    **Prediction of Stray Capacitance of CM Chokes and its Influence on EMI Filters**  
Mohammad Ali, Rehnuma Bushra, Jens Friebe, Axel Mertens, Leibniz University Hannover, D; Mathias Magdowski, Ralf Vick, Otto-von-Guericke-University, D
- 241**                    **Non-Inductive Highly Efficient Power Transfer System, a New Approach**  
Michael Zenkner, Heinz Zenkner, WPT-Systems, D
- 242**                    **A Novel Design for a 22KW Transformer for a 3 Phase Full Bridge LLC EV Onboard Charger for Smaller Size, Lower Cost and Improved Performance**  
Gerard Healy, Pulse Electronics.com, IRL
- 243**                    **Common Mode DGS EMI Filter Integrated into a GaN Half Bridge Switching Cell**  
Eduard Dechant, Norbert Seliger, Rosenheim University of Applied Sciences, D; Ralph Kennel, Technical University of Munich, D
- 244**                    **Capacitance- and Thermally-Wise Optimized Transformers**  
Christian Dietmann, Tobias Appel, Daniel Benner, STS Spezial-Transformatoren-Stockach, D; Klaus F. Hoffmann, Michael Meissner, Norman Landskron, Christian Bödeker, Helmut-Schmidt-University, D;

## Renewable Energies

- 245**                    **Experimental Design of Solar DC Microgrid for the Rural Electrification of Africa**  
Lucas Richard, Marie-Cecile Alvarez-Herault, Bertrand Raison, David Frey, Alexis Derby, G2elab, F
- 246**                    **Generation of Encoder Signals for the Coupling of a Wind Turbine Converter to Model-Based Controlled Converter**  
Dawid Koczy, Alexander Ernst, Wilfried Holzke, Bernd Orlik, University of Bremen, D
- 247**                    **Magnetic Design for Three Phase PV Inverters with DC-Link Referenced Output Filter**  
Asier Garcia-Bediaga, Itsasne Landaburu, Victor Lopez, Alejandro Rujas, Luis Mir, Ikerlan, E
- 248**                    **Development of a Distributed Measurement System for the Digitalisation of a Wind Turbine**  
René Reimann, Alexander Ernst, Wilfried Holzke, Steffen Menzel, Holger Raffel, Bernd Orlik, University of Bremen, D; Arne Schulz, Axtrion, D
- 249**                    **Provision of Power Plant Equal Ancillary Services by Wind Turbines: From Maximum to Grid-demanded Power Point Tracking**  
David Matthies, Alexander Ernst, Henning Sauerland, René Reimann, Wilfried Holzke, Bernd Orlik, University of Bremen, D

**250**                    **Impact of 1200V SiC Modules in an Industrial PV Power Unit**  
Victor Lopez, Luis Mir, Alejandro Rujas, Ikerlan, E; Carlos Martinez de Guereñu, AEG Power Solutions, E; Aritz Egea, Mondragon University, E; Jose M. Bermejo, Ingeteam Power Technology, E

**251**                    **A GaN-Based DC-DC Converter with Zero Voltage Switching and Hysteretic Current Control for 99% Efficient Bidirectional Charging of Electrocaloric Capacitive Loads**  
Stefan Mönch, Michael Basler, Kareem Mansour, Rüdiger Quay, Richard Reiner, Patrick Waltereit, Fraunhofer Institute IAF, D; David Bach, Kilian Bartholome, Roland Binninger, Fraunhofer Institute IPM, D; Sylvia Gebhardt, Christian Molin, Fraunhofer Institute IKTS, D

**252**                    **Magnetic Component Design for Medium Voltage Photovoltaic Application**  
Michael Schmidhuber, Christoph Drexler, Jonas Pfeiffer, SUMIDA Components & Modules, D; **David** Derix, Michael Geiss, Jürgen Thoma, Fraunhofer Institute ISE, D

### Multilevel Converter

**253**                    **Novel Approach to Characterize Li-ion Battery Cells for the Purpose of Battery Emulation by Fitting of the Isolated Cell Dynamics**  
Julian Estaller, Ali Mashayekh, Johannes Buberger, Tobias Högerl, Mahdiye Khorasani, Manuel Kuder, Richard Eckerle, Thomas Weyh, Universität der Bundeswehr München, D

**254**                    **Derating Strategies for a Modular Multilevel Converter**  
Raul Santiago Munoz-Aguilar, Ilknur Colak, Shan Jiang, Maschinenfabrik Reinhausen, D

**255**                    **Model Predictive Control for 17-Levels Inverter in PV systems**  
Mohamed Abdelrahem, Mostafa Ahmed, Ralph Kennel, Ibrahim Harbi, Technical University of Munich, D; M. Saad Bin Arif, Aligarh Muslim University, IND

**256**                    **Three-Level ANPC Converter as an Input Stage of an EV Charging System with Bipolar DC Link**  
Michal Harasimczuk, Jacek Rabkowski, Bartosz Lasek, Rafal Kopacz, Krzysztof Kalinowski, Rafal Miskiewicz, Warsaw University of Technology, PL

**257**                    **A Fast and Safe Discharging Method for MMC Submodule Capacitors**  
Ilknur Colak, Maschinenfabrik Reinhausen, D; Mohammad Abu-Ali, Technical University of Munich, D

**258**                    **Investigation of Different Driver Topologies for Application in Modular Multilevel Systems**  
Wolfgang Grupp, Tobias Högerl, Andreas Wiedenmann, Julian Estaller, Nina Sorokina, Manuel Kuder, Richard Eckerle, Thomas Weyh, Universität der Bundeswehr München, D

**259**                    **Modeling and Estimation of the Losses of a Multi-Level Inverter with Integrated Battery for Electric Vehicles**  
Gaël Pongnot, Clément Mayet, Denis Labrousse, SATIE Laboratory, F

## Energy Storage and Grids

- 260**                    **Design and Limit of a 4 Legs Inverter with Unbalanced Grid Injection Operation Connected to a Quad Active Bridge Converter**  
Antoine Bulteau, Yves Lembeye, David Frey, G2elab, F
- 261**                    **Online State of Health Diagnostic Method of Battery cells in a Reconfigurable Battery System or Multilevel Inverter**  
Ali Mashayekh, Mahdiye Khorasani, Julian Estaller, Johannes Buberger, Richard Eckerle, Manuel Kuder, Thomas Weyh, Universität der Bundeswehr München, D
- 262**                    **Dynamic Study of Resonant Converters for Lithium-Ion Battery Charger Applications**  
Christian Branas, Francisco Azcondo, Francisco J. Díaz, Rosario Casanueva, Alberto Pigazo, University of Cantabria, E; Juan C. Viera, University of Oviedo, E
- 263**                    **Monitoring Considerations of Second Life Lithium Ion Batteries in Battery Energy Storage Systems**  
Mussab Najeeb, Technical University of Ilmenau, D; Ulf Schwalbe, Fulda University of Applied Sciences, D
- 264**                    **Test Bench for the Investigation of Resonances in Low-Voltage Grids**  
Swen Bosch, Jochen Staiger, Heinrich Steinhart, Aalen University of Applied Sciences, D
- 265**                    **Improved Predictive Energy Management for Stationary Energy Storage Systems - Multi-Use of Different Applications**  
Lukas Böhning, Ulf Schwalbe, Mathias Herget, Fulda University of Applied Sciences, D
- 266**                    **Interconnection of Point-to-Point HVDC Links to Form a Multi-Terminal HVDC Grid**  
Steffen Menzel, Alexander Ernst, René Reimann, Wilfried Holzke, Holger Raffel, Bernd Orlik, University of Bremen, D
- 267**                    **Toward the Deployment of Low-Voltage DC Distribution Grids: Review on the Influence of Voltage Levels, Protection Schemes and Power Quality Aspects**  
César Augusto Slongo, Alvaro Llaría, ESTIA Institute of Technology, F; Geoffrey Auran, EDF, F; Florian Perrotton, Enedis, F
- 268**                    **Comparative Implementation of a two-stage DC-Link**  
Dirk Fischer, Regine Mallwitz, Robert Rohn, Technical University of Braunschweig, D

## E-Mobility and other Transportations

- 269**                    **Comprehensive Performance Evaluation of Discrete 1200V IGBT7 S7 for Drives Application**  
Andrea Piccioni, Infineon Technologies, A

- 270            **Design and Control of a Power Electronics Load Emulator based on Industrial Inverters**  
Christian Sack, Fabian Mink, THM University of Applied Sciences, D; Stephan Beineke, Matthias Bachmann, Alexander Bähr, KEBA Industrial Automation, D
- 271            **Benefits of Using the New 1200V Si IGBT and SiC MOSFET Modules for E-Bus Application**  
Miroslav Hruska, Siemens Advanta Development, CZ; Vladislav Damec, VSB-Technical University of Ostrava, CZ; Martin Kozak, Siemens Digital Industries, CZ
- 272            **Saliency-Based Dynamic Encoderless Operation of Two Induction Machines in Parallel Configuration**  
Markus Vogelsberger, Alstom, A; Hans Ertl, Eduardo Rodriguez Montero, Thomas Wolbank, Technical University of Vienna, A; Wolfram Teppan, LEM Advisory Services, CH
- 273            **Fault-Tolerant Regenerative Sensorless Braking of PMAC Motors Enables Degraded Mode of Operation for Functional Safety**  
Tobias Schmidt, Jens Onno Krahl, Cologne University of Applied Sciences, D; Joachim Holtz, University of Wuppertal, D; Freddy Heinzelmann, SEW-EURODRIVE, D
- 274            **Low Power, High Isolation Voltage Transformer Testing: Energy Storage, Charging Systems and EV**  
Shreyankh Krishnamurthy, Pulse Electronics, D
- 275            **On-Board Power Management in a Marine Autonomous Surface Vehicle (ASV): Multi-Port Transformer Design**  
Thierry Martiré, Guillaume Pellecuer, University of Montpellier, F; Mickaël Petit, Benjamin Loyer, SATIE Laboratory, F

## Packaging II

- 276            **Stackpac®  
The Smart Chip Package Concept of Possehl Electronics**  
Dietmar Kurzeja, Volker Berg, Possehl Electronics, D
- 277            **On the Importance of Thermo-Mechanical Properties Mismatch Management on Power Module to Cooler System Attachment**  
Francois Le Henaff, Allan Borja, Huawei Technologies, D
- 278            **Thick Film Copper Bonding for Highly Reliable Ag Free Metal Ceramic Substrates**  
André Schwöbel, Daniel Schnee, Heraeus, D
- 279            **Modeling and Thermal Analysis of the ACEPACK SMIT Package in H-Bridge High Voltage Circuits**  
Marco Papasero, Angelo Giuseppe Sciacca, Gaetano Bazzano, Ludovica Longo, Alessandra Cascio, STMicroelectronics, I; Giacomo Scelba, Mario Cacciato, Arjun Sujeeth, Andrea Cusumano, University of Catania, I
- 280            **New Die Attach Materials: Silver and Silver/ Copper Sintering Pastes**  
Battist Rábay, Adrian Stelzer, Nano-Join, D

- 281**                    **Novel Material Technology Reduces Tool and Fixturing Complexity for Solder Preforms in Power Module Assembly**  
Joseph Hertline, Andreas Karch, Indium, USA; Aaron Hutzler, Bond Pulse, D
- 282**                    **Compact Half-Bridge Module for a Charger Application Utilizing GaN Power Devices with Integrated Driver**  
Julian Weimer, Dominik Koch, Ingmar Kallfass, University of Stuttgart, D
- 283**                    **Influence of TIM and Encapsulation on Power Cycling Capability of Discrete Devices**  
Erping Deng, Yushan Zhao, Luhong Xie, Jianhui Liu, Yongzhang Huang, North China Electric Power University, CHN